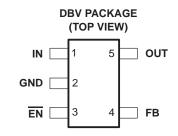
# TPS76201 LOW OUTPUT ADJUSTABLE ULTRALOW-POWER 100-mA LDO LINEAR REGULATOR

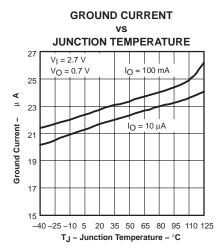
SLVS323B - FEBRUARY 2001 - REVISED JANUARY 2007

- 100-mA Low-Dropout Regulator
- Adjustable Output Voltage (0.7 V to 5.5 V)
- Only 23 μA Quiescent Current at 100 mA
- 1 μA Quiescent Current in Standby Mode
- Over Current Limitation
- -40°C to 125°C Operating Junction Temperature Range
- 5-Pin SOT-23 (DBV) Package

### description

The TPS76201 low-dropout (LDO) voltage regulator features an adjustable output voltage as low as 0.7 V. It is an ideal regulator for sub 1.2-V DSP core voltage supplies and is equally suited for similar applications with other low-voltage processors and controllers. SOT-23 packaging and the high-efficiency that results from the regulator's ultralow power operation make the TPS76201 especially useful in handheld and portable battery applications. This regulator features low dropout voltages and ultralow quiescent current compared to conventional LDO





regulators. Offered in a 5-terminal small outline integrated-circuit SOT-23 package, the TPS76201 is ideal for micropower operations and where board space is at a premium.

A combination of new circuit design and process innovation has enabled the usual PNP pass transistor to be replaced by a PMOS pass element. Since the PMOS pass element is a voltage-driven device, the quiescent current is ultralow (30  $\mu$ A maximum) and is stable over the entire range of output load current (10  $\mu$ A to 100 mA). Intended for use in portable systems such as laptops and cellular phones, the ultralow-power operation results in a significant increase in the system battery operating life.

The TPS76201 also features a logic-enabled sleep mode to shut down the regulator, reducing quiescent current to 1  $\mu$ A typical at T<sub>J</sub> = 25°C. The TPS76201 is offered in an adjustable version (programmable over the range of 0.7 V to 5.5 V).

#### AVAILABLE OPTIONS†

TJ	VOLTAGE	PACKAGE	PART N	SYMBOL	
–40°C to 125°C	Variable 0.7 V to 5.5 V	SOT-23 (DBV)	TPS76201DBVT‡	TPS76201DBVR§	PFUI

<sup>†</sup> Contact the factory for availability of fixed output options.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.



<sup>&</sup>lt;sup>‡</sup> The DBVT indicates tape and reel of 250 parts.

<sup>§</sup> The DBVR indicates tape and reel of 3000 parts.

# TPS76201 LOW OUTPUT ADJUSTABLE ULTRALOW-POWER 100-mA LDO LINEAR REGULATOR

SLVS323B - FEBRUARY 2001 - REVISED JANUARY 2007

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Input voltage range (see Note 1)	0.3 V to 13.5 V
Voltage range at EN	
Voltage on OUT, FB	7 V
Peak output current	Internally limited
ESD rating, HBM	2 kV
Continuous total power dissipation	See Dissipation Rating Table
Operating virtual junction temperature range, T <sub>J</sub>	–40°C to 150°C
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network ground terminal.

#### **DISSIPATION RATING TABLE**

BOARD	PACKAGE	$R_{ heta JC}$	$R_{\theta JA}$	DERATING FACTOR $T_A \le 25^{\circ}C$ ABOVE $T_A = 25^{\circ}C$ POWER RATING		T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING	
Low K‡	DBV	65.8°C/W	259°C/W	3.9 mW/°C	386 mW	212 mW	154 mW	
High K§	DBV	65.8°C/W	180°C/W	5.6 mW/°C	555 mW	305 mW	222 mW	

<sup>‡</sup> The JEDEC Low K (1s) board design used to derive this data was a 3 inch x 3 inch, two layer board with 2 ounce copper traces on top of the board. § The JEDEC High K (2s2p) board design used to derive this data was a 3 inch x 3 inch, multilayer board with 1 ounce internal power and ground planes and 2 ounce copper traces on top and bottom of the board.

#### recommended operating conditions

	MIN	NOM	MAX	UNIT
Input voltage, V <sub>I</sub> (see Note 2)	2.7		10	V
Output voltage range, VO	0.7		5.5	V
Continuous output current, IO (see Note 3)	0.01		100	mA
Operating junction temperature, TJ	-40		125	°C

- NOTES: 2. To calculate the minimum input voltage for your maximum output current, use the following formula:  $V_{Imin} = V_{Omax} + V_{DO}(max load)$ 
  - 3. Continuous output current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.



# TPS76201 LOW OUTPUT ADJUSTABLE ULTRALOW-POWER 100-mA LDO LINEAR REGULATOR

SLVS323B - FEBRUARY 2001 - REVISED JANUARY 2007

# electrical characteristics over recommended operating free-air temperature range, V<sub>I</sub> = V<sub>O(typ)</sub> + 1 V, I<sub>O</sub> = 100 mA, $\overline{EN}$ = 0 V, C<sub>O</sub> = 4.7 $\mu$ F (unless otherwise noted)

PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT	
Outrot wells as (40, A to 400 as A locally (see Aleta 4)	$0.7 \text{ V} \le \text{V}_{\text{O}} \le 5.5 \text{ V},$	T <sub>J</sub> = 25°C		٧o		V	
Output voltage (10 µA to 100 mA load) (see Note 4)	$0.7 \text{ V} \le \text{V}_{\text{O}} \le 5.5 \text{ V},$	$T_J = -40^{\circ}C$ to $125^{\circ}C$	0.97V <sub>O</sub>		1.03V <sub>O</sub>	7 /	
Quiescent current (GND current)	EN = 0V, 10 μA < I <sub>O</sub> < 100 mA	T <sub>J</sub> = 25°C		23			
(see Notes 4 and 5)	EN = 0 V, 10 μA < I <sub>O</sub> < 100 mA	$T_J = -40^{\circ}C \text{ to } 125^{\circ}C,$			30	μΑ	
Load regulation	$\overline{\text{EN}} = 0 \text{ V},$ 10 $\mu\text{A} < \text{I}_{\text{O}} < 100 \text{ mA}$	T <sub>J</sub> = 25°C		12		mV	
	2.7 V < V <sub>I</sub> ≤ 10 V, See Note 4	T <sub>J</sub> = 25°C,		0.04		%/V	
Output voltage line regulation (ΔV <sub>O</sub> /V <sub>O</sub> ) (see Note 5)	$2.7 \text{ V} < \text{V}_{\text{I}} \le 10 \text{ V},$ $\text{T}_{\text{J}} = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C},$	See Note 4			0.1	76/ V	
Output noise voltage	BW = 300 Hz to 50 kH $V_O = 0.7 V$ ,	z, C <sub>O</sub> = 10 μF, T <sub>J</sub> = 25°C		60		μVRMS	
Output current limit	V <sub>O</sub> = 0 V,	See Note 4		350	750	mA	
Cton div., accurant	EN = V∣,	2.7 < V <sub>I</sub> < 10 V		1		μΑ	
Standby current	$T_J = -40^{\circ}C \text{ to } 125^{\circ}C$				2	μΑ	
FB input current	FB = 0.666 V		-1		1	μΑ	
High level enable input voltage	2.7 V < V <sub>I</sub> < 10 V		1.7			V	
Low level enable input voltage	2.7 V < V <sub>I</sub> < 10 V				0.8	V	
Power supply ripple rejection	f = 1 kHz, T <sub>J</sub> = 25°C,	$C_0 = 10 \mu F$ , See Note 4		60		dB	
Land surrent (FAI)	EN = 0 V		-1	0	1	μΑ	
Input current (EN)	EN = V <sub>I</sub>		-1		1	μА	

NOTES: 4. Minimum IN operating voltage is 2.7 V or  $V_{O(typ)}$  + 1 V, whichever is greater. Maximum IN voltage 10 V, minimum output current 10  $\mu$ A, maximum output current 100 mA.

5. If  $V_0 \le 1.8 \text{ V}$  then  $V_{1min} = 2.7 \text{ V}$ ,  $V_{1max} = 10 \text{ V}$ :

Line Reg. (mV) = 
$$(\%/V) \times \frac{V_O(V_{Imax} - 2.7 V)}{100} \times 1000$$

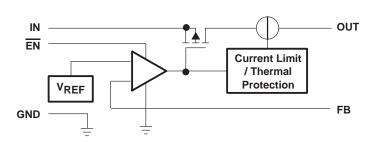
If  $V_O \ge 2.5 \text{ V}$  then  $V_{lmin} = V_O + 1 \text{ V}$ ,  $V_{lmax} = 10 \text{ V}$ :

Line Reg. (mV) = 
$$(\%/V) \times \frac{V_O(V_{Imax} - (V_O + 1 V))}{100} \times 1000$$



### functional block diagram

#### TPS76201



#### **Terminal Functions**

TERMII	NAL	1/0	DECORPORTION
NAME	NO.	1/0	DESCRIPTION
GND	2 Ground		Ground
EN 3 I		I	Enable input
FB	4	I	Feedback voltage
IN	IN 1 I Input supply voltage		Input supply voltage
OUT 5 O Regulated output voltage		0	Regulated output voltage

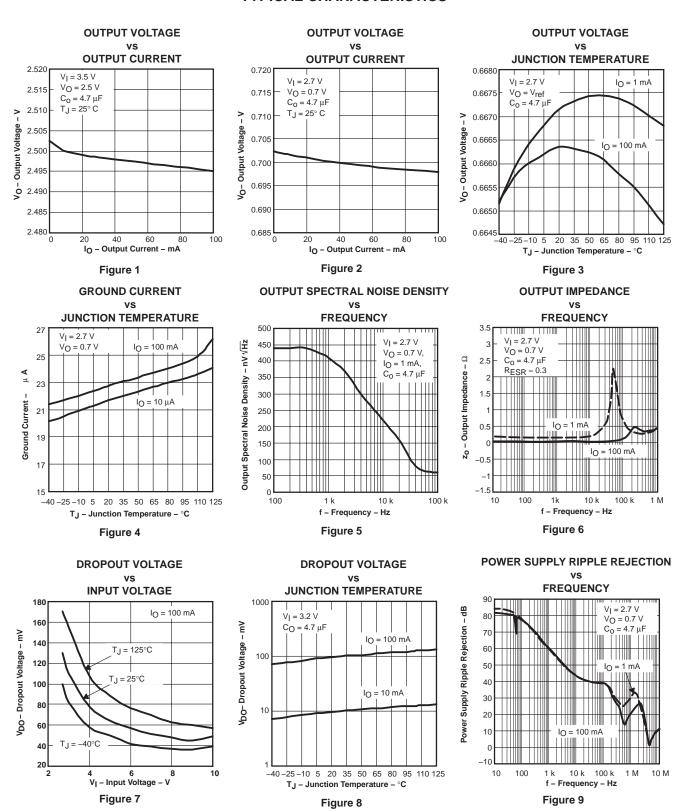
### **TYPICAL CHARACTERISTICS**

# **Table of Graphs**

			FIGURE
	0	vs Output current	1, 2
Vo	Output voltage	vs Junction temperature	3
	Ground current	vs Junction temperature	4
	Output spectral noise density	vs Frequency	5
z <sub>O</sub>	Output impedance	vs Frequency	6
V <sub>DO</sub>	Daniel and and the man	vs Input voltage	7
۷DO	Dropout voltage	vs Junction temperature	8
	Power supply ripple rejection	vs Frequency	9
	Output voltage and enable voltage	vs Time (start-up)	10
	Line transient response		11, 13
	Load transient response		12, 14
	Equivalent series resistance (ESR)	vs Output current	15, 16



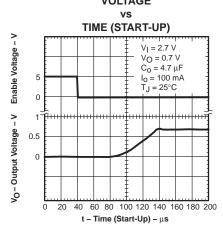
#### TYPICAL CHARACTERISTICS

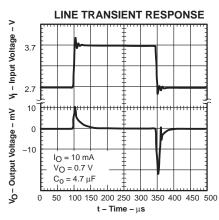




#### TYPICAL CHARACTERISTICS

# OUTPUT VOLTAGE AND ENABLE VOLTAGE





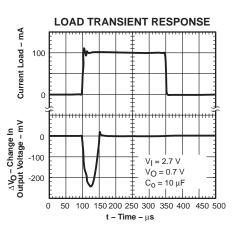


Figure 10

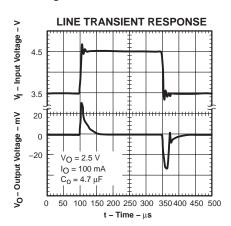


Figure 11

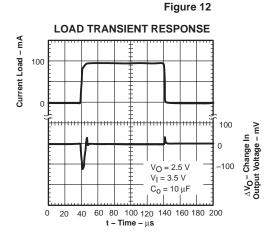


Figure 13



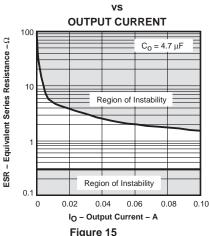
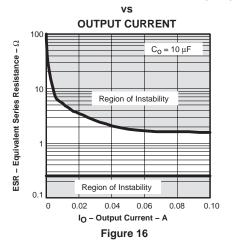


Figure 14

# TYPICAL REGIONS OF STABILITY EQUIVALENT SERIES RESISTANCE (ESR)



TEXAS INSTRUMENTS www.ti.com

# SLVS323B – FEBRUARY 2001 – REVISED JANUARY 2007

#### APPLICATION INFORMATION

The TPS76201 low-dropout (LDO) regulator has been optimized for use in battery-operated equipment including, but not limited to, the sub 1.2-V DSP core voltage supplies. It features low quiescent current (23  $\mu$ A nominally) and enable inputs to reduce supply currents to 1  $\mu$ A when the regulators are turned off.

A typical application circuit is shown in Figure 17.

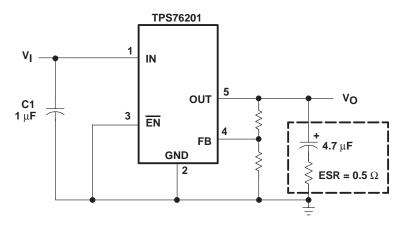


Figure 17. Typical Application Circuit

#### external capacitor requirements

Although not required, a 0.047- $\mu$ F or larger ceramic input bypass capacitor, connected between IN and GND and located close to the TPS76201, is recommended to improve transient response and noise rejection. A higher-value electrolytic input capacitor may be necessary if large, fast-rise-time load transients are anticipated and the device is located several inches from the power source.

Like all low dropout regulators, the TPS76201 requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance is 4.7  $\mu\text{F}$ . The ESR (equivalent series resistance) of the capacitor should be between 0.3  $\Omega$  and 1.5  $\Omega$ . to ensure stability. Capacitor values larger than 4.7  $\mu\text{F}$  are acceptable, and allow the use of smaller ESR values. Capacitances less than 4.7  $\mu\text{F}$  are not recommended because they require careful selection of ESR to ensure stability. Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described above. Most of the commercially available 4.7  $\mu\text{F}$  surface-mount solid tantalum capacitors, including devices from Sprague, Kemet, and Nichico, meet the ESR requirements stated above. Multilayer ceramic capacitors may have very small equivalent series resistances and may thus require the addition of a low value series resistor to ensure stability.

#### **CAPACITOR SELECTION**

PART NO.	MFR.	VALUE	MAX ESR†	SIZE $(H \times L \times W)^{\ddagger}$
T494B475K016AS	KEMET	4.7 μF	$1.5~\Omega$	$1.9 \times 3.5 \times 2.8$
195D106x0016x2T	SPRAGUE	10 μF	$1.5~\Omega$	$1.3\times7.0\times2.7$
695D106x003562T	SPRAGUE	10 μF	$1.3~\Omega$	$2.5\times7.6\times2.5$
TPSC475K035R0600	AVX	4.7 μF	$0.6~\Omega$	$2.6 \times 6.0 \times 3.2$

<sup>†</sup> ESR is maximum resistance in Ohms at 100 kHz and T<sub>A</sub> = 25°C. Contact manufacturer for minimum ESR values.



<sup>‡</sup> Size is in mm.

#### APPLICATION INFORMATION

#### output voltage programming

The output voltage of the TPS76201 adjustable regulator is programmed using an external resistor divider as shown in Figure 18. The output voltage is calculated using:

$$V_{O} = V_{ref} \times \left(1 + \frac{R1}{R2}\right) \tag{1}$$

Where:

V<sub>ref</sub> = 0.6663 V typ (the internal reference voltage)

Resistors R1 and R2 should be chosen for approximately 10- $\mu$ A divider current. Lower value resistors can be used but offer no inherent advantage and waste more power. Higher values should be avoided as leakage currents at FB increase the output voltage error. The recommended design procedure is to choose R2 = 66.5 k $\Omega$  to set the divider current at 10  $\mu$ A and then calculate R1 using:

$$R1 = \left(\frac{V_{O}}{V_{ref}} - 1\right) \times R2 \tag{2}$$

# OUTPUT VOLTAGE PROGRAMMING GUIDE

OUTPUT VOLTAGE		ESISTANCE $\Omega$ )‡		
(V)	R1	R2		
0.7	3.36	66.5		
0.9	23.2	66.5		
1.2	53.6	66.5		
1.5	83.5	66.5		
1.8	113	66.5		
2.5	182	66.5		
3.3	246	66.5		
3.6	294	66.5		
4	332	66.5		
5	432	66.5		

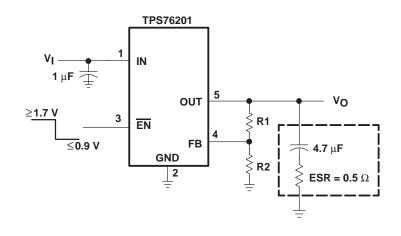


Figure 18. TPS76201 Adjustable LDO Regulator Programming



<sup>&</sup>lt;sup>‡</sup>1% values shown.

#### SLVS323B - FEBRUARY 2001 - REVISED JANUARY 2007

#### **APPLICATION INFORMATION**

#### power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of  $125^{\circ}$ C; the maximum junction temperature should be restricted to  $125^{\circ}$ C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation,  $P_{D(max)}$ , and the actual dissipation,  $P_{D}$ , which must be less than or equal to  $P_{D(max)}$ .

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_{J}max - T_{A}}{R_{\theta JA}}$$

Where:

T<sub>J</sub>max is the maximum allowable junction temperature.

R<sub>0.1A</sub> is the thermal resistance junction-to-ambient for the package, see the dissipation rating table.

 $T_A$  is the ambient temperature.

The regulator dissipation is calculated using:

$$P_D = (V_I - V_O) \times I_O$$

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation will trigger the thermal protection circuit.

#### regulator protection

The TPS76201 PMOS-pass transistor has a built-in back diode that conducts reverse current when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. If extended reverse voltage operation is anticipated, external limiting might be appropriate.

The TPS76201 features internal current limiting and thermal protection. During normal operation, the TPS76201 limits output current to approximately 350 mA. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds approximately 165°C, thermal-protection circuitry shuts it down. Once the device has cooled down to below approximately 140°C, regulator operation resumes.







11-Apr-2013

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
TPS76201DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PFUI	Samples
TPS76201DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PFUI	Samples
TPS76201DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PFUI	Samples
TPS76201DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PFUI	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.





11-Apr-2013

#### OTHER QUALIFIED VERSIONS OF TPS76201:

Automotive: TPS76201-Q1

NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

# PACKAGE MATERIALS INFORMATION

17-Oct-2011 www.ti.com

### TAPE AND REEL INFORMATION

#### **REEL DIMENSIONS**





#### **TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width								
В0	Dimension designed to accommodate the component length								
K0	Dimension designed to accommodate the component thickness								
W	Overall width of the carrier tape								
P1	Pitch between successive cavity centers								

#### TAPE AND REEL INFORMATION

#### \*All dimensions are nominal

Device	Package	Package	Pins	SPQ	Reel	Reel	Α0	В0	K0	P1	W	Pin1
	Туре	Drawing			Diameter (mm)	Width W1 (mm)	(mm)	(mm)	(mm)	(mm)	(mm)	Quadrant
TPS76201DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS76201DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

www.ti.com 17-Oct-2011



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS76201DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS76201DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0

DBV (R-PDSO-G5)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-178 Variation AA.



# DBV (R-PDSO-G5)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



#### IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

#### Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom **Amplifiers** amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors <a href="www.ti.com/omap">www.ti.com/omap</a> TI E2E Community <a href="e2e.ti.com">e2e.ti.com</a>

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>